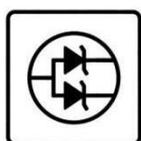


MSKSEMI 美森科

SEMICONDUCTOR



ESD



TVS



TSS



MOV



GDT



PLED

AO4882-MS

Product specification

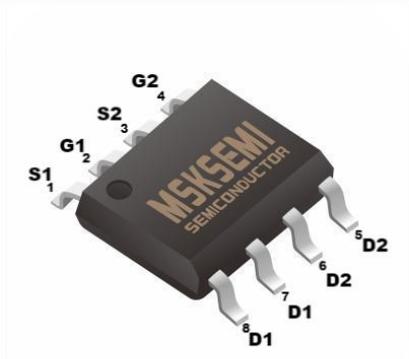
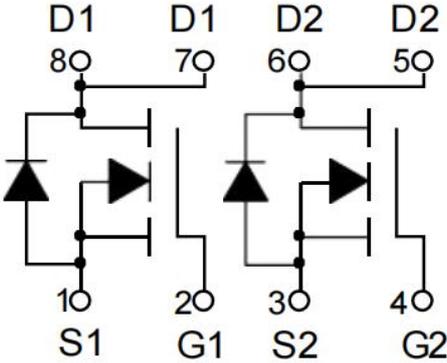
General Features

- $V_{DS} = 40V$ $I_D = 6A$
- $R_{DS(ON)} < 30m\Omega$ @ $V_{GS}=10V$

Application

- Battery protection
- Load switch
- Uninterruptible power supply

Reference News

PACKAGE OUTLINE	Pin Configuration	Marking
		
SOP-8	N-Channel MOSFET	

Absolute Maximum Ratings (TA=25 unless otherwise noted)

Symbol	Parameter	Rating	Units
V _{DS}	Drain- Source Voltage	40	V
V _{GS}	Gate- Source Voltage	±20	V
I _D @ T _A = 25 °C	Continuous Drain Current ¹	6	A
I _D @ T _A = 70 °C	Continuous Drain Current ¹	4	A
I _{DM}	Pulsed Drain Current ²	36	A
EAS	Single Pulse Avalanche Energy ³	31	mJ
I _{AS}	Avalanche Current	25	A
P _D @ T _A = 25 °C	Total Power Dissipation ⁴	1.9	W
T _{STG}	Storage Temperature Range	-55 to 150	°C
T _J	Operating Junction Temperature Range	-55 to 150	°C
R _{θJA}	Thermal Resistance Junction-ambient ¹ (t≤10s)	40	°C/W
	Thermal Resistance Junction- ambient ¹	65	°C/W

Electrical Characteristics (T_J=25 °C, unless otherwise noted)

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
BV _{DSS}	Drain- Source Breakdown Voltage	V _{GS} =0V , I _D =250uA	40	---	---	V
Δ BV _{DSS} /Δ T _J	BVDSS Temperature Coefficient	Reference to 25°C , I _D =1 mA	---	0.032	---	V/°C
R _{DS(ON)}	Static Drain-Source On-Resistance ²	V _{GS} =10V , I _D =6A	---	25	30	mΩ
		V _{GS} =4.5V , I _D =4A	---	35	45	
V _{GS(th)}	Gate Threshold Voltage		1.2	1.6	2.5	V
Δ V _{GS(th)}	V _{GS(th)} Temperature Coefficient	V _{GS} =V _{DS} , I _D =250uA	---	-4.8	---	MV/°C
I _{DSS}	Drain- Source Leakage Current	V _{DS} =32V , V _{GS} =0V , T _J =25°C	---	---	1	uA
		V _{DS} =32V , V _{GS} =0V , T _J =55°C	---	---	5	
I _{GSS}	Gate- Source Leakage Current	V _{GS} = ± 20V , V _{DS} =0V	---	---	± 100	nA
g _{fs}	Forward Transconductance	V _{DS} =5V , I _D =6A	---	32	---	S
R _g	Gate Resistance	V _{DS} =0V , V _{GS} =0V , f=1MHz	---	2.1	---	
Q _g	Total Gate Charge (4.5V)		---	9.8	---	nC
Q _{gs}	Gate- Source Charge	V _{DS} =32V , V _{GS} =4.5V , I _D =6A	---	2.8	---	
Q _{gd}	Gate- Drain Charge		---	3.9	---	
T _{d(on)}	Turn- On Delay Time		---	2.8	---	ns
T _r	Rise Time	V _{DD} =20V , V _{GS} =10V ,	---	40.4	---	
T _{d(off)}	Turn-Off Delay Time	R _G =3.3 I _D =6A	---	22.8	---	
T _f	Fall Time		---	6.4	---	
C _{iss}	Input Capacitance		---	1013	---	pF
C _{oss}	Output Capacitance	V _{DS} =15V , V _{GS} =0V , f=1MHz	---	107	---	
C _{rss}	Reverse Transfer Capacitance		---	76	---	
I _S	Continuous Source Current ^{1,5}		---	---	8	A
I _{SM}	Pulsed Source Current ^{2,5}	V _G =V _D =0V , Force Current	---	---	36	A
V _{SD}	Diode Forward Voltage ²	V _{GS} =0V , I _S =1A , T _J =25°C	---	---	1	V
t _{rr}	Reverse Recovery Time	I _F =7A , di/dt=100A/μs ,	---	10	---	nS
Q _{rr}	Reverse Recovery Charge	T _J = 25 °C	---	3.3	---	nC

Note :

- 1.The data tested by surface mounted on a 1 inch 2 FR-4 board with 2OZ copper.
- 2.The data tested by pulsed , pulse width ≅ 300us , duty cycle ≅ 2%
- 3.The EAS data shows Max. rating . The test condition is V_{DD}=25V,V_{GS}=10V,L=0.1mH,I_{AS}=25A
- 4.The power dissipation is limited by 150°C junction temperature
- 5.The data is theoretically the same as I_D and I_{DM} , in real applications , should be limited by total power dissipation.

Typical Characteristics

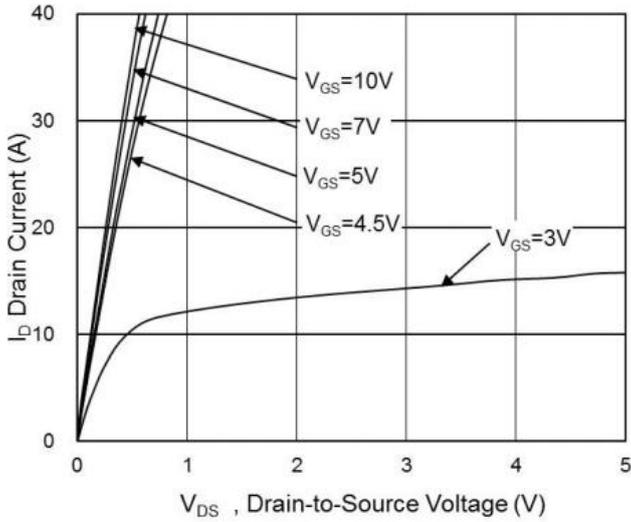


Fig.1 Typical Output Characteristics

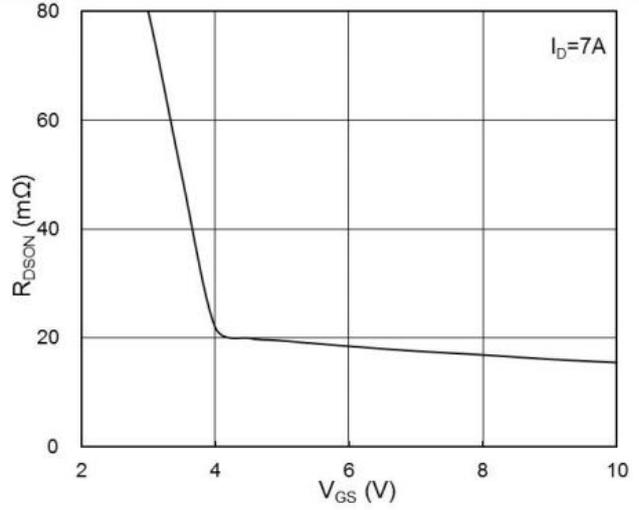


Fig.2 On-Resistance vs. G-S Voltage

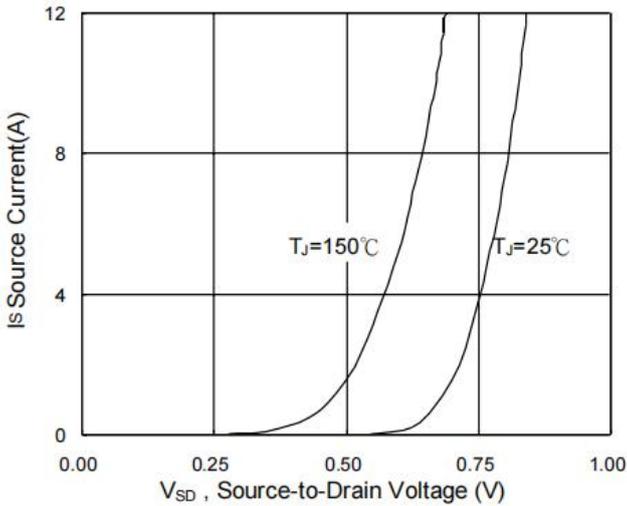


Fig.3 Forward Characteristics of Reverse

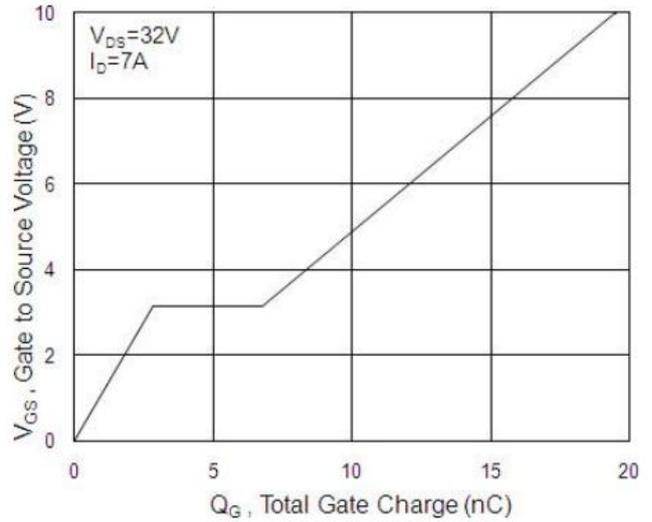


Fig.4 Gate-Charge Characteristics

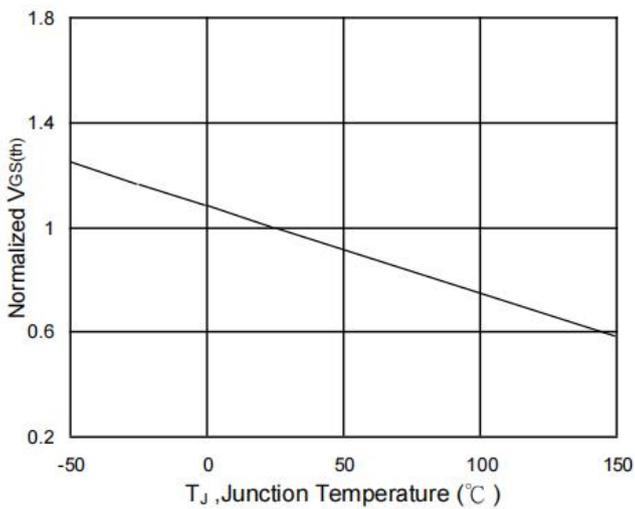


Fig.5 Normalized $V_{GS(th)}$ vs. T_J

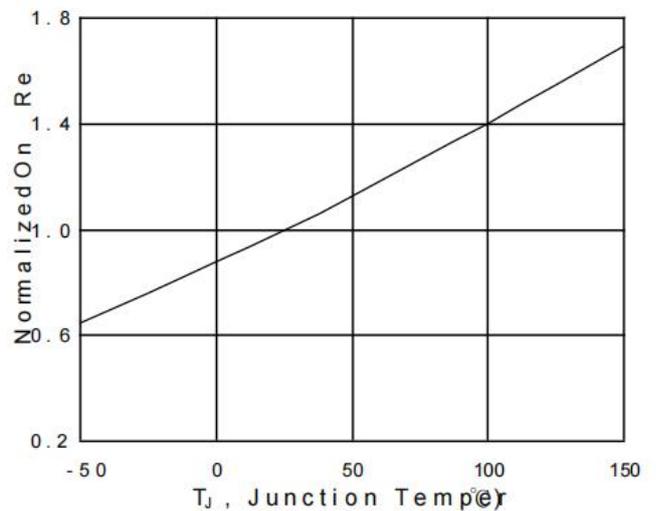


Fig.6 Normalized $R_{DS(on)}$ vs. T_J

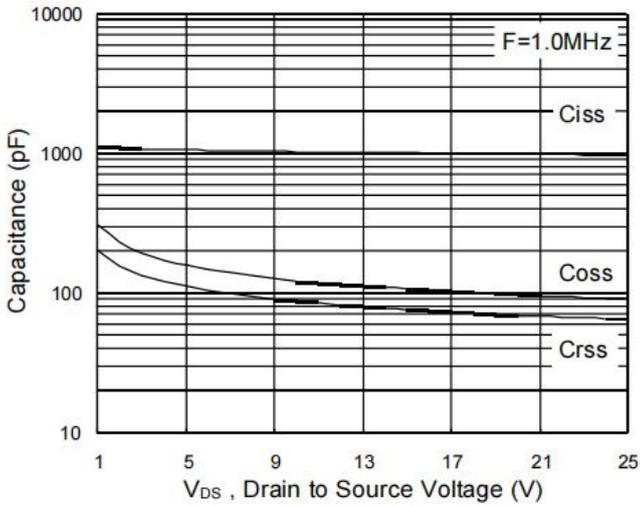


Fig.7 Capacitance

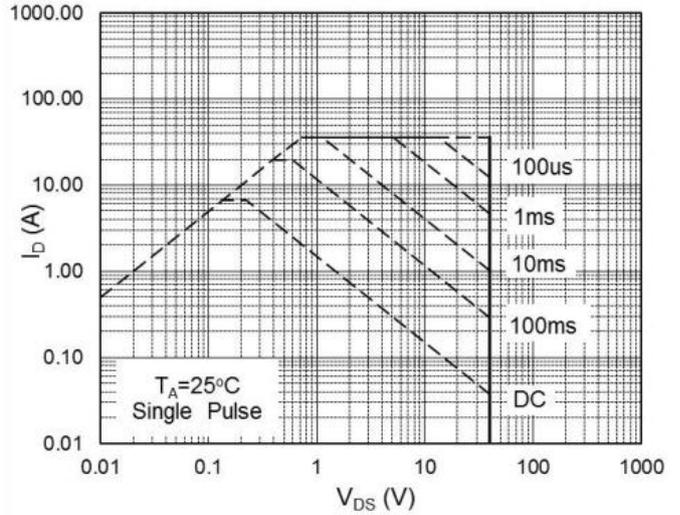


Fig.8 Safe Operating Area

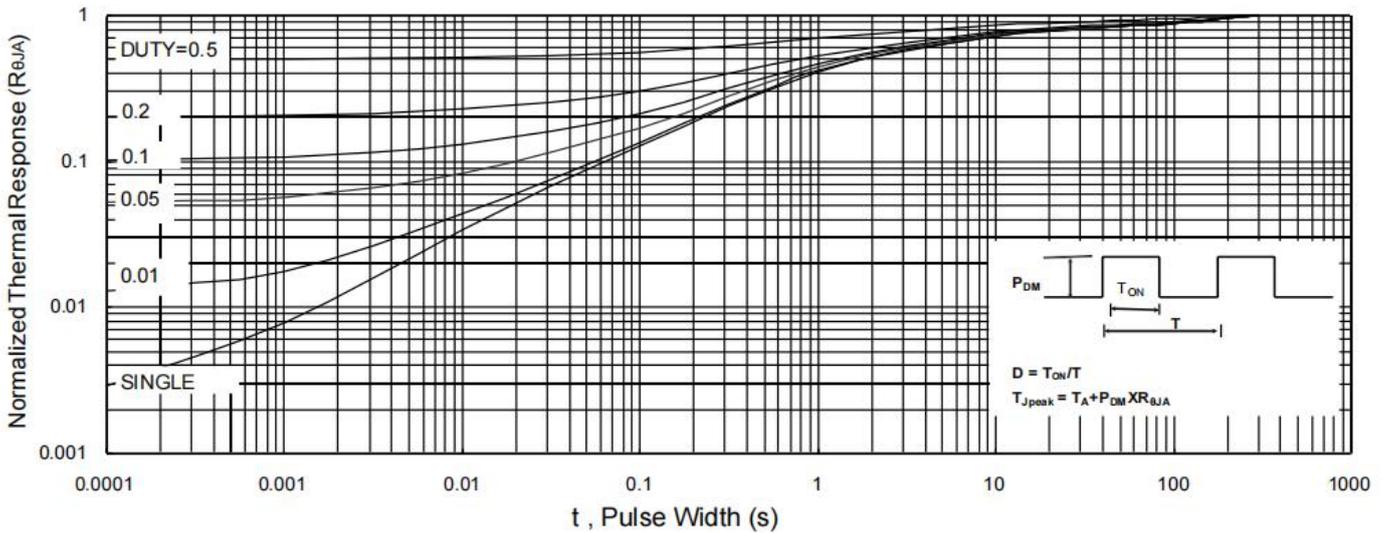


Fig.9 Normalized Maximum Transient Thermal Impedance

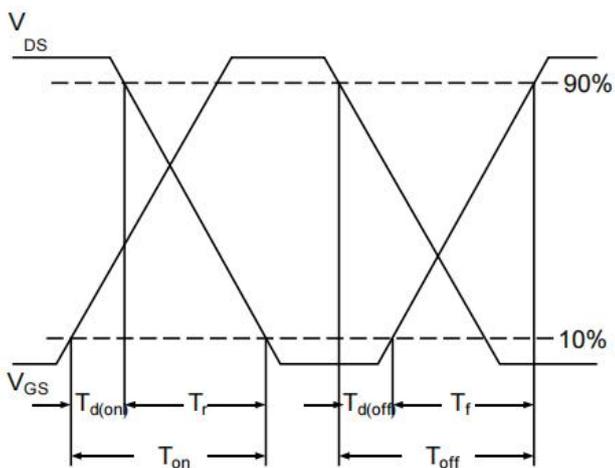


Fig.10 Switching Time Waveform

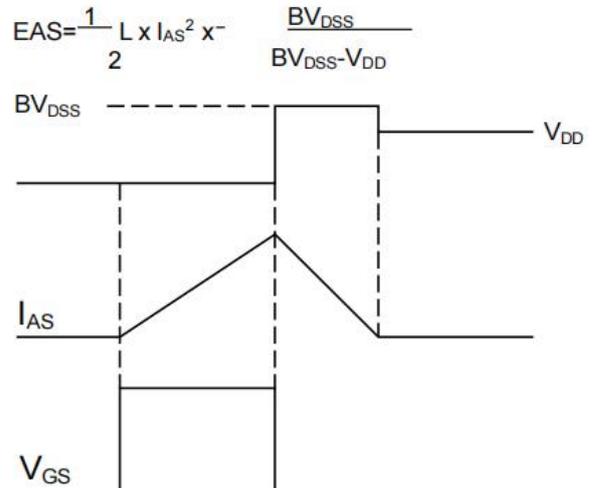
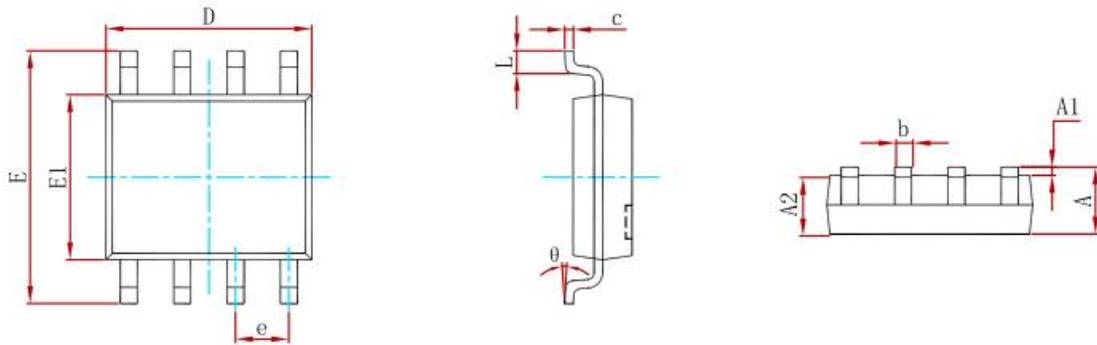


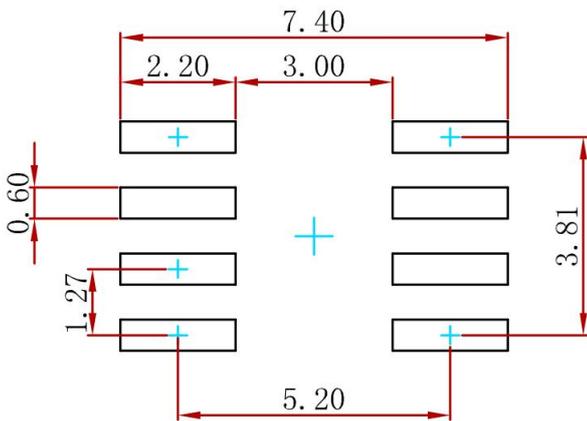
Fig.11 Unclamped Inductive Switching Waveform

PACKAGE MECHANICAL DATA



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min	Max	Min	Max
A	1.350	1.750	0.053	0.069
A1	0.100	0.250	0.004	0.010
A2	1.350	1.550	0.053	0.061
b	0.330	0.510	0.013	0.020
c	0.170	0.250	0.007	0.010
D	4.800	5.000	0.189	0.197
e	1.270 (BSC)		0.050 (BSC)	
E	5.800	6.200	0.228	0.244
E1	3.800	4.000	0.150	0.157
L	0.400	1.270	0.016	0.050
θ	0°	8°	0°	8°

Suggested Pad Layout



Note:

1. Controlling dimension: in millimeters.
2. General tolerance: ±0.05mm.
3. The pad layout is for reference purposes only

REEL SPECIFICATION

P/N	PKG	QTY
AO4882-MS	SOP-8	3000

Attention

- Any and all MSKSEMI Semiconductor products described or contained herein do not have specifications that can handle applications that require extremely high levels of reliability, such as life-support systems, aircraft's control systems, or other applications whose failure can be reasonably expected to result in serious physical and/or material damage. Consult with your MSKSEMI Semiconductor representative nearest you before using any MSKSEMI Semiconductor products described or contained herein in such applications.
- MSKSEMI Semiconductor assumes no responsibility for equipment failures that result from using products at values that exceed, even momentarily, rated values (such as maximum ratings, operating condition ranges, or other parameters) listed in products specifications of any and all MSKSEMI Semiconductor products described or contained herein.
- Specifications of any and all MSKSEMI Semiconductor products described or contained herein stipulate the performance, characteristics, and functions of the described products in the independent state, and are not guarantees of the performance, characteristics, and functions of the described products as mounted in the customer's products or equipment. To verify symptoms and states that cannot be evaluated in an independent device, the customer should always evaluate and test devices mounted in the customer's products or equipment.
- MSKSEMI Semiconductor strives to supply high-quality high-reliability products. However, any and all semiconductor products fail with some probability. It is possible that these probabilistic failures could give rise to accidents or events that could endanger human lives, that could give rise to smoke or fire, or that could cause damage to other property. When designing equipment, adopt safety measures so that these kinds of accidents or events cannot occur. Such measures include but are not limited to protective circuits and error prevention circuits for safe design, redundant design, and structural design.
- In the event that any or all MSKSEMI Semiconductor products (including technical data, services) described or contained herein are controlled under any of applicable local export control laws and regulations, such products must not be exported without obtaining the export license from the authorities concerned in accordance with the above law.
- No part of this publication may be reproduced or transmitted in any form or by any means, electronic or mechanical, including photocopying and recording, or any information storage or retrieval system, or otherwise, without the prior written permission of MSKSEMI Semiconductor.
- Information (including circuit diagrams and circuit parameters) herein is for example only ; it is not guaranteed for volume production. MSKSEMI Semiconductor believes information herein is accurate and reliable, but no guarantees are made or implied regarding its use or any infringements of intellectual property rights or other rights of third parties.
- Any and all information described or contained herein are subject to change without notice due to product/technology improvement, etc. When designing equipment, refer to the "Delivery Specification" for the MSKSEMI Semiconductor product that you intend to use.